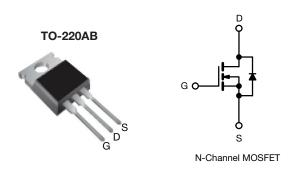
www.vishay.com

Vishay Siliconix

HALOGEN

FREE

EF Series Power MOSFET With Fast Body Diode



PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	650				
R _{DS(on)} typ. (Ω) at 25 °C	V _{GS} = 10 V	0.059			
Q _g max. (nC)	77				
Q _{gs} (nC)	19				
Q _{gd} (nC)	16				
Configuration	Single				

FEATURES

- 4th generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free and halogen-free	SiHP068N60EF-GE3

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V_{DS}	600		
Gate-source voltage			V_{GS}	± 30	V	
Continuous drain current (T _J = 150 °C)	V _{GS} at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	- I _D	41	A	
	V _{GS} at 10 V	T _C = 100 °C		26		
Pulsed drain current ^a			I _{DM}	115		
Linear derating factor				2	W/°C	
Single pulse avalanche energy b			E _{AS}	226	mJ	
Maximum power dissipation			P_{D}	250	W	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C		
Drain-source voltage slope	T _J = 125 °C		4).//d+	100	1//20	
Reverse diode dV/dt d		dV/dt	50	V/ns		
Soldering recommendations (peak temperature) ^c	For 10 s			260	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 120 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 4 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, di/dt = 210 A/ μ s, starting T_J = 25 °C



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THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	LIMIT	UNIT	
Maximum junction-to-ambient	R_{thJA}	62	°C/W	
Maximum junction-to-case (drain)	R_{thJC}	0.5	G/VV	

SPECIFICATIONS (T _J = 25 °C, u	SYMBOL	· · · · · · · · · · · · · · · · · · ·					UNIT
Static	STWIBOL	IES	IVIIIV.	ITP.	WAX.	ONIT	
	\/	1 1/	= 0 V, I _D = 250 μA	600	Ι	1	V
Drain-source breakdown voltage	V _{DS}	46	-	0.63	-	V/°C	
V _{DS} temperature coefficient	ΔV _{DS} /T _J		Reference to 25 °C, I _D = 1 mA				
Gate-source threshold voltage (N)	V _{GS(th)}		V_{GS} , $I_D = 250 \mu A$	3	-	5	V
Gate-source leakage	I_{GSS}	$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
			$V_{GS} = \pm 30 \text{ V}$		-	±1	μA
Zero gate voltage drain current	I _{DSS}		V _{DS} = 480 V, V _{GS} = 0 V		-	1	μA
			, V _{GS} = 0 V, T _J = 125 °C	-	-	2	mA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 16 A	-	0.059	0.068	Ω
Forward transconductance	9 _{fs}	V _{DS}	= 30 V, I _D = 16 A	_	9	_	S
Dynamic		T		1	1	1	
Input capacitance	C _{iss}	$V_{GS} = 0 V$,		-	2628	-	
Output capacitance	C _{oss}		$V_{DS} = 100 \text{ V},$		122	-	
Reverse transfer capacitance	C _{rss}	f = 1 MHz		-	7	-	
Effective output capacitance, energy related ^a	$C_{\text{o(er)}}$	V _{DS} = 0 V to 480 V, V _{GS} = 0 V		-	87	-	pF -
Effective output capacitance, time related ^b	C _{o(tr)}			-	543	-	
Total gate charge	Qg			-	51	77	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 16 \text{ A}, V_{DS} = 480 \text{ V}$		19	-	nC
Gate-drain charge	Q _{gd}				16	-	
Turn-on delay time	t _{d(on)}	V _{DD} = 480 V, I _D = 16 A,		-	27	54	
Rise time	t _r			-	55	83	- ns
Turn-off delay time	t _{d(off)}	V _{GS} =	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		53	80	
Fall time	t _f			-	35	70	
Gate input resistance	Rq	f = 1 MHz, open drain		0.3	0.7	1.4	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I _S	MOSFET sym	MOSFET symbol		_	41	
Pulsed diode forward current	I _{SM}	integral reverse p - n junction diode		-	-	115	A
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 16 A, V _{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t _{rr}				152	304	ns
Reverse recovery charge	Q _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 16 \text{ A},$ $di/dt = 100 \text{ A/µs}, V_R = 400 \text{ V}$		-	1	2	μC
Reverse recovery current	I _{RRM}				14	_	A

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}

b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

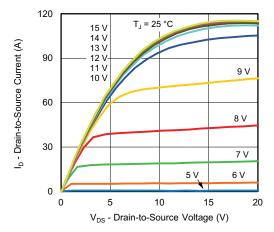


Fig. 1 - Typical Output Characteristics

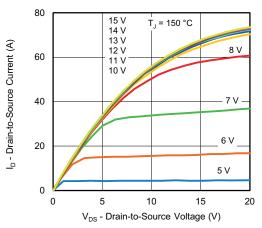


Fig. 2 - Typical Output Characteristics

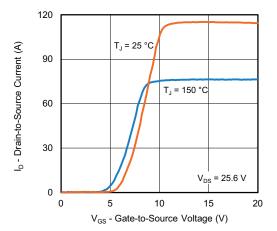


Fig. 3 - Typical Transfer Characteristics

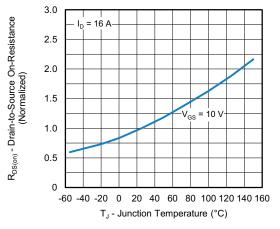


Fig. 4 - Normalized On-Resistance vs. Temperature

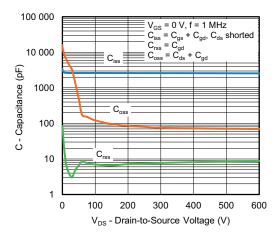


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

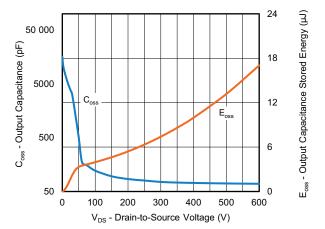


Fig. 6 - Coss and Eoss vs. VDS



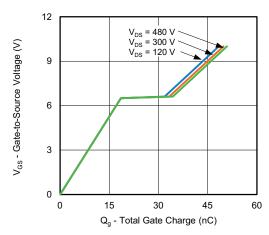


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

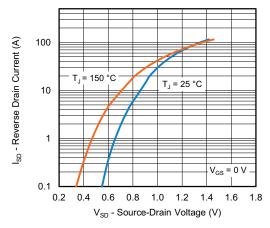


Fig. 8 - Typical Source-Drain Diode Forward Voltage

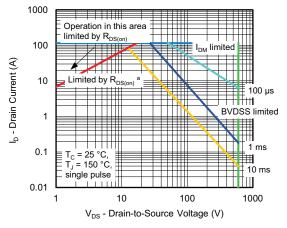


Fig. 9 - Maximum Safe Operating Area

Note

a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

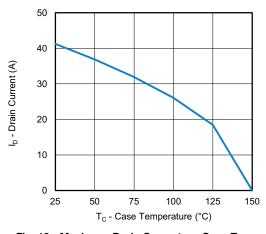


Fig. 10 - Maximum Drain Current vs. Case Temperature

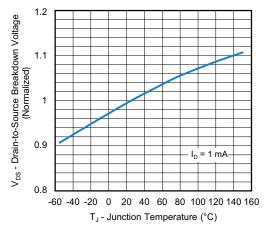


Fig. 11 - Temperature vs. Drain-to-Source Voltage



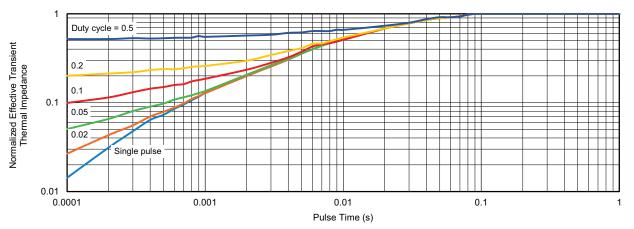


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

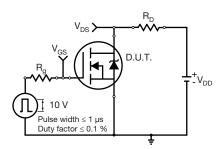


Fig. 13 - Switching Time Test Circuit

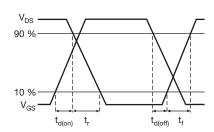


Fig. 14 - Switching Time Waveforms

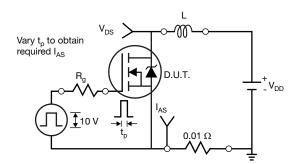


Fig. 15 - Unclamped Inductive Test Circuit

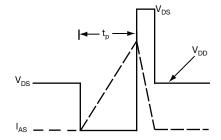


Fig. 16 - Unclamped Inductive Waveforms

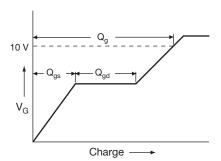


Fig. 17 - Basic Gate Charge Waveform

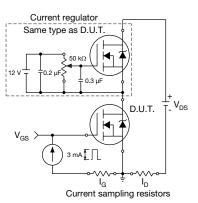
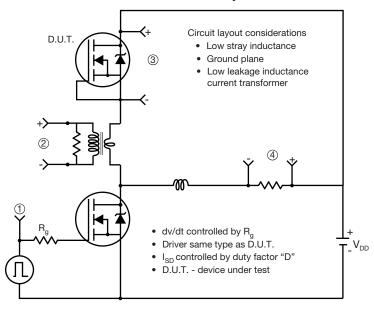


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



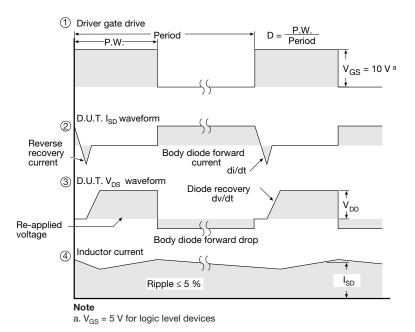


Fig. 19 - For N-Channel

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